



# System Level Tools for Power and Thermal

Docea Power Gene Matter, VP Application Engineering

Power saving can reach  
40–70% if handled  
at the Electronic System Level

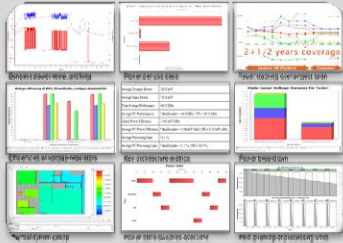
# Explore

# Develop

# Validate

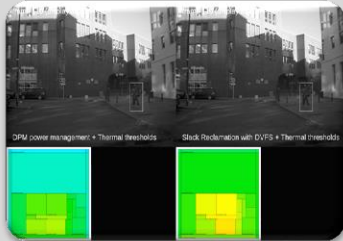
- Early power-thermal exploration, dimensioning and "landing zone"
  - What-if investigation: power consumption, floor planning, assembly/package options
    - Power profiles inputs: from spreadsheets, traces, characterized data from existing design
- Implementation phase
  - Supports Power planning with feedback from thermal behavior
  - Non-regression tests
  - Converge/refine Power/Thermal behavior during implementation
    - Power profiles inputs: power traces from emulators, RTL/Gate level power analysis tools
- Validation phase
  - Replaces thermal probes (often missing or not exact placement) for debug and analysis
    - Power profiles inputs: measurements, power probing

# Where is your area of concern ?



Early power-thermal-performance trade-off exploration and architecture specification

Use Case power budget tracking



Power-thermal aware software development and validation



Thermal exploration and validation

# What is the Impact of using the wrong thermal scenario?

Most Thermal Studies Use Simplistic Scenarios due to length of Transient Simulations in CFD tools

Select costly  
(and un-competitive) packaging ?

Live with reduced  
margins ?

Drop projects that  
could have been  
competitive with  
the right  
packaging?



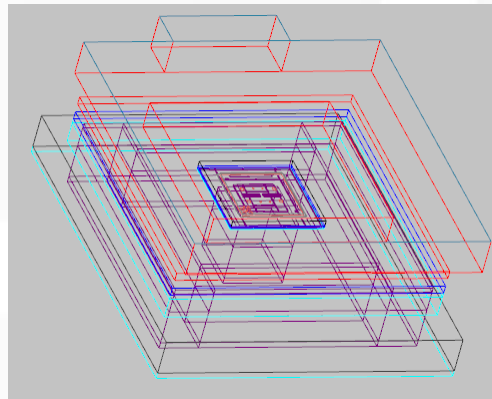
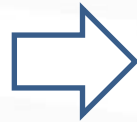
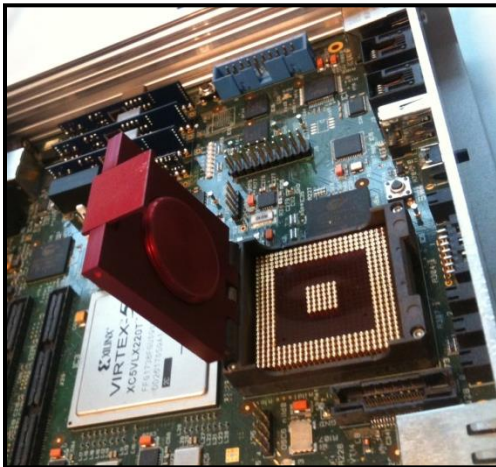
Select a cost  
competitive  
packaging and  
take a risk ?

What if it fails?

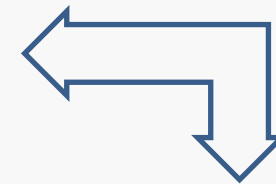


# Validation Support

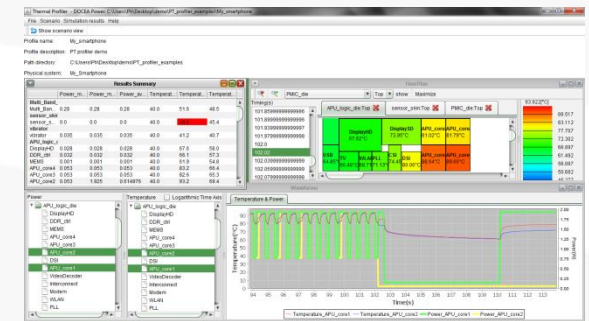
- How can I validate the power and thermal behavior on packaged devices?
  - Limited number of thermal sensors
  - Limited number of observable power ports
- Use power-thermal model!



Power traces from Validation boards

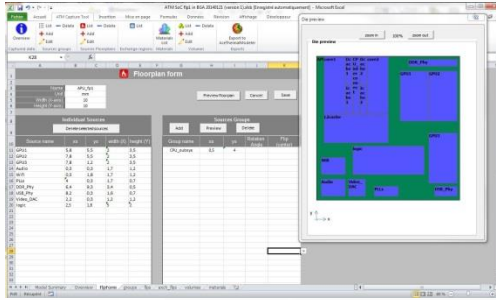


Inside behaviour

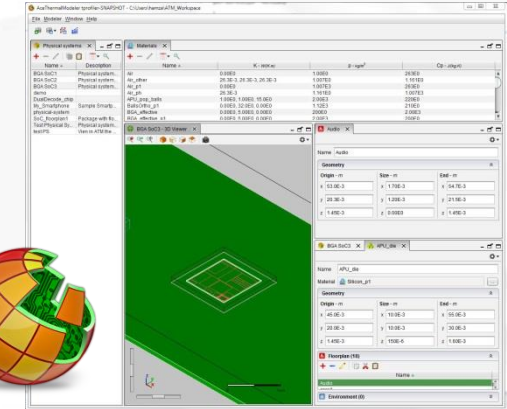


# Solution Overview

MODELING



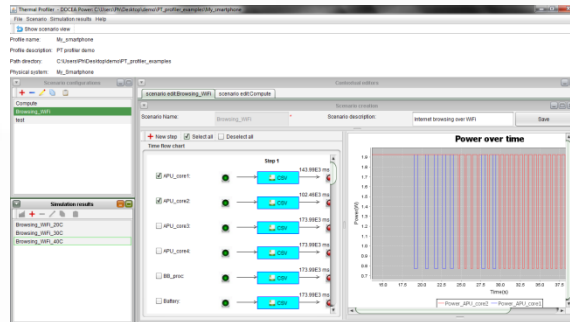
CFD Import  
Thermal Model Capture Tool  
3D geometry, floorplans, materials,  
heat exchange surfaces



Compact Thermal Model  
Generation



SIMULATION



Simulation Set-up Environment



Result Dashboard

# ESL Power Thermal Simulation

- Enables compact thermal models generation that are a few **100 nodes multi-source** models:
  - Suitable for transient simulations and dynamic thermal management modeling
- Using Thermal Models for **exploring floorplans** and **dynamic use cases**:
  - Power Architects can perform what-if analysis and take into account thermal issues at a very early stage.
  - Shorter loop cycles between thermal Experts and System Architect/Engineering teams.
- Calculate the power/temperature coupling:
  - **Power profiles obtained at an assumed constant temperature can be corrected for more accurate power estimations.**

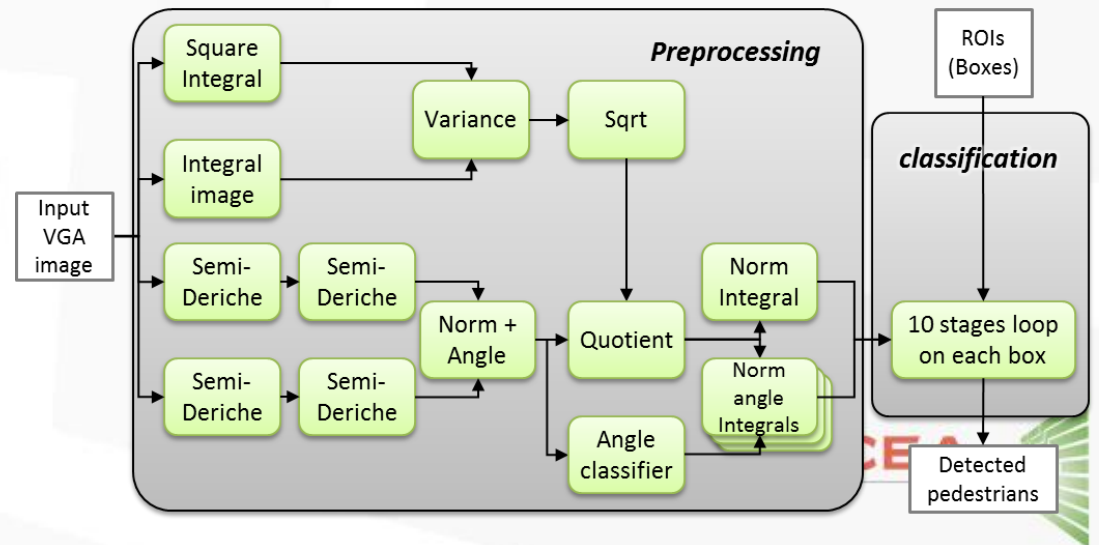
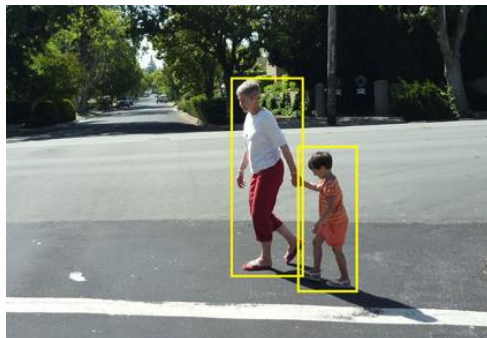
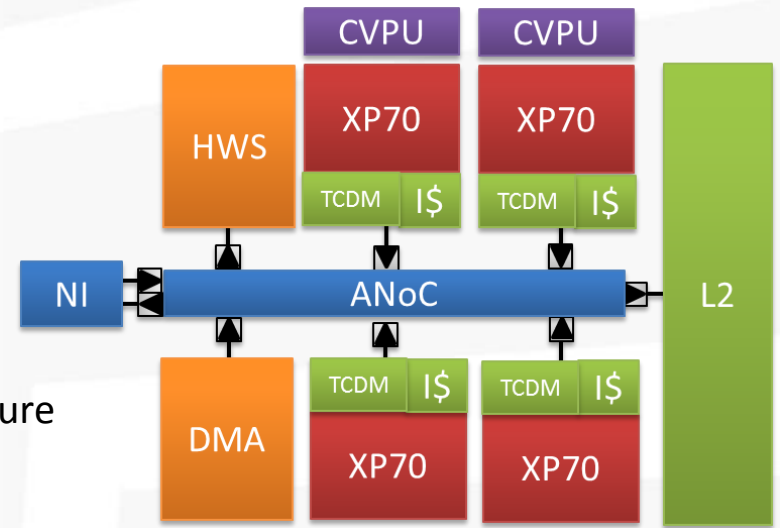
# Power/Thermal aware software development:

Example of thermal management policies Co-  
simulated with a Virtual Platform

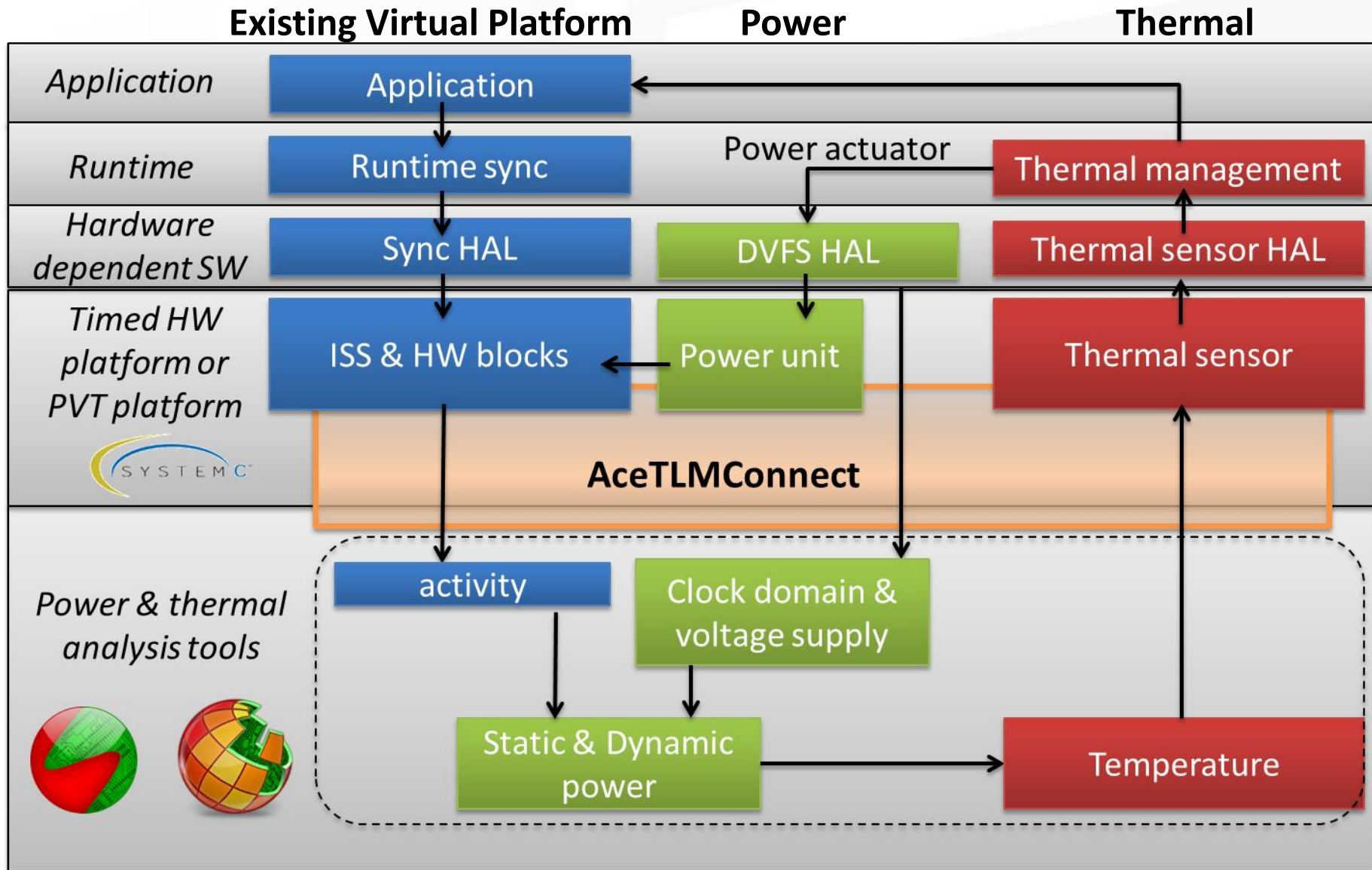


# MPSoC use case: LOCOMOTIV

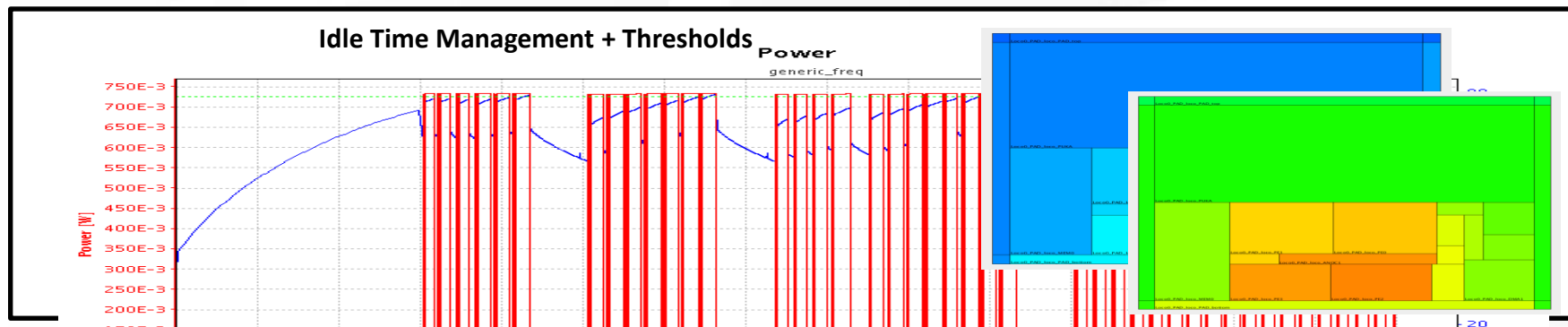
- LOCOMOTIV architecture
  - Multi-Core with shared memory
  - Thermal sensors
  - Power management
    - Local: adapts to process/ageing/temperature
    - Global: DVFS control per core
  - Hardware Assisted Runtime Software (HARS)
- Pedestrian Detection Application
  - Variable execution time
  - Parallel execution



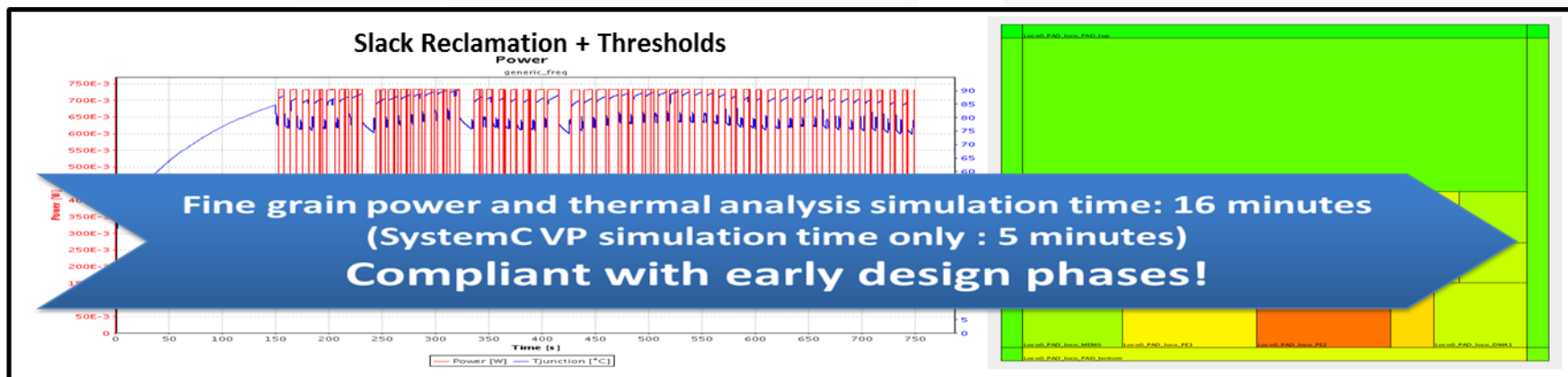
# Power & Thermal Aware Virtual Platform



# Thermal Management Policy Comparison

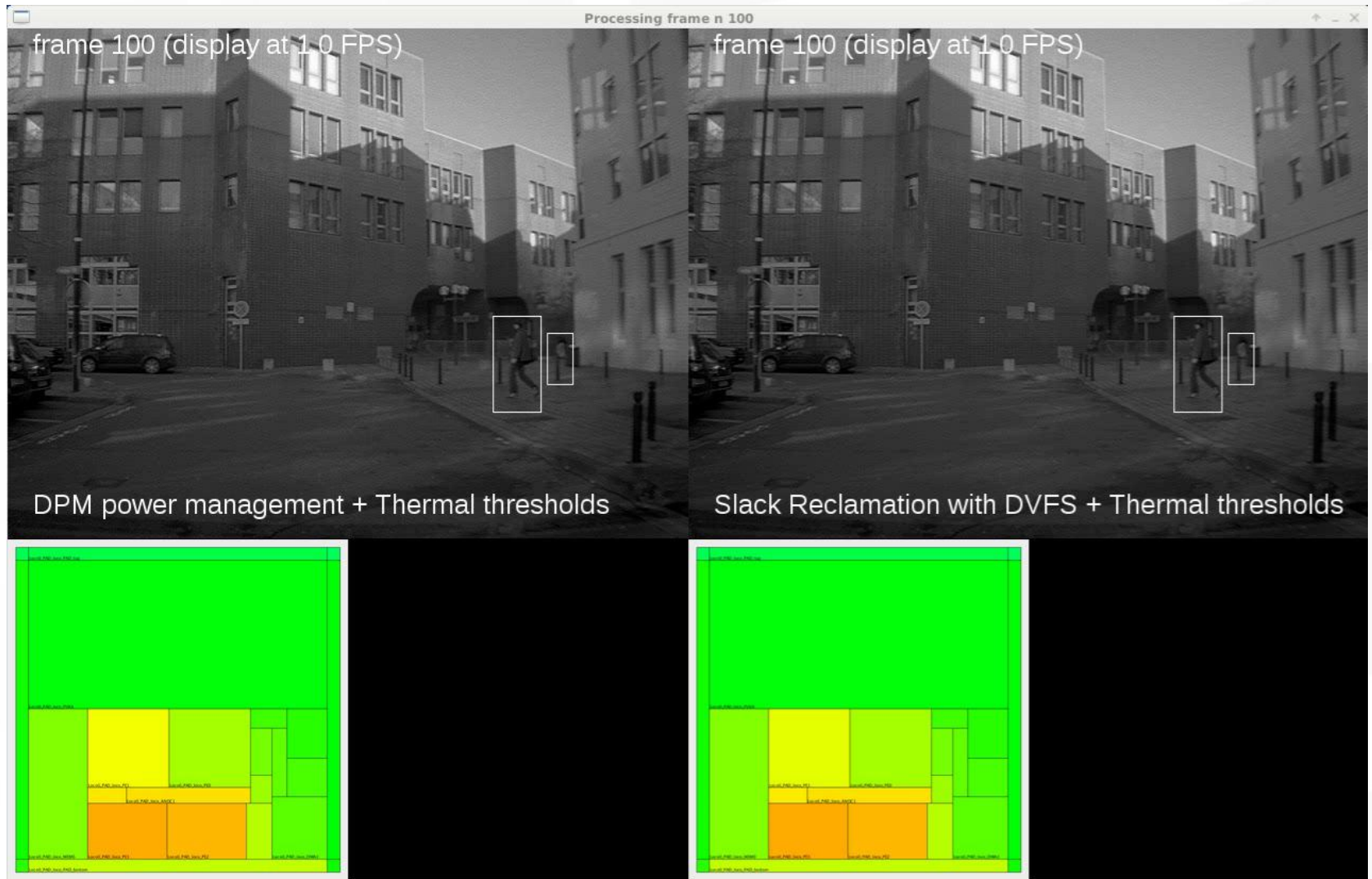


Thermal budget respected :  $T < 95^{\circ}\text{C}$   
 Using thresholds :  $70^{\circ}\text{C} < T < 90^{\circ}\text{C}$   
 Peak temperature =  $90,71^{\circ}\text{C}$   
 Thermal control works but with poor application results :  
 Skipped frames : 10/52 **but successive frames !**



Thermal budget respected :  $T < 95^{\circ}\text{C}$ , same thresholds :  $70^{\circ}\text{C} < T < 90^{\circ}\text{C}$   
 Peak temperature =  $91,2^{\circ}\text{C}$   
 Slack reclamation : allocate remaining time to next frame (data dependency)  
 Skipped frames : 3/52. **Application rendering is preserved.**

# Validation with real software



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POWER



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